

As a below named inventor, I hereby declare that my residence, post office address and citizenship are as stated below next to my name, and I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled: APPARATUS FOR SPIN-COATING SEMICONDUCTOR, the specification of which (check one)

☒ SUBSTRATE AND METHOD OF DOING THE SAME  
☒ is attached hereto.  
☐ was filed on \_\_\_\_\_ as United States Application Number or PCT International Application Number \_\_\_\_\_ on \_\_\_\_\_, and was amended on \_\_\_\_\_ (if applicable).

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above. I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulation, § 1.56. I hereby claim foreign priority benefits under Title 35, United States Code, § 119/365 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate disclosing the subject matter claimed in this application and having a filing date (1) before that of the application on which priority is claimed, or (2) if no priority is claimed before the filing date of this application.

#### Prior foreign Application(s)

Number	Country	Day/Month/Year Filed	Priority Claimed
10-346766	Japan	7/12/1998	(X) Yes ( ) No
_____	_____	_____	( ) Yes ( ) No
_____	_____	_____	( ) Yes ( ) No
_____	_____	_____	( ) Yes ( ) No
_____	_____	_____	( ) Yes ( ) No

I hereby claim the benefit under Title 35, United States Code, § 120/365 of any United States application(s) listed below and PCT International Applications listed above or below, and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulation, § 1.56 which became available between the filing date of the prior application and the national or PCT international filing date of this application.

#### Prior U.S. Provisional, Nonprovisional and/or PCT Application(s)

Application Number	Day/Month/Year Filed	Status (Patented, Pending, Abandoned)	Priority Claimed
_____	_____	_____	( ) Yes ( ) No
_____	_____	_____	( ) Yes ( ) No

I hereby appoint Beth E. Arnold, Reg. No. 35,430; Charles H. Cella, Reg. No. 38,099; John C. Gorecki, Reg. No. 38,471; Edward J. Kelly, Reg. No. 38,936; Donald W. Muirhead, Reg. No. 33,978; and Matthew P. Vincent, Reg. No. 36,709 as attorneys to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith.

Address all telephone calls to Donald W. Muirhead at telephone number (617) 832-1257.

Address all correspondence to:  
 Patent Group  
 Foley, Hoag & Eliot LLP  
 One Post Office Square  
 Boston, MA 02109-2170

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Inventor's signature Shunichi Furuya Date November 25, 1999  
 Full name of sole or first inventor (given name, family name) SHUNICHI FURUYA Citizenship Japanese  
 Residence Tokyo, Japan  
 Post Office Address (include zip code) c/o NEC Corporation, 7-1, Shiba 5-chome, Minato-ku, Tokyo, Japan Date \_\_\_\_\_  
 Inventor's signature \_\_\_\_\_ Date \_\_\_\_\_  
 Full name of inventor (given name, family name) \_\_\_\_\_ Citizenship \_\_\_\_\_  
 Residence \_\_\_\_\_ Date \_\_\_\_\_  
 Post Office Address (include zip code) \_\_\_\_\_ Date \_\_\_\_\_  
 Inventor's signature \_\_\_\_\_ Date \_\_\_\_\_  
 Full name of inventor (given name, family name) \_\_\_\_\_ Citizenship \_\_\_\_\_  
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 Full name of inventor (given name, family name) \_\_\_\_\_ Citizenship \_\_\_\_\_  
 Residence \_\_\_\_\_ Date \_\_\_\_\_  
 Post Office Address (include zip code) \_\_\_\_\_ Date \_\_\_\_\_

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